

EPO-TEK® 377
Technical Data Sheet
For Reference Only
High Temperature Epoxy

Date: Apr 2014 Recommended Cure: 150°C / 1 Hour

Rev: VI

No. of Components: Two Mix Ratio by Weight: 1:1

Specific Gravity: Part A: 1.15 Part B: 1.22

Pot Life: 24 Hours

**Shelf Life:** One year at room temperature

NOTE: Container(s) should be kept closed when not in use. Filled systems should be stirred thoroughly before mixing and prior to use.

<u>Product Description:</u> EPO-TEK<sup>®</sup> 377 is a two component, high Tg, fiber optic grade epoxy. It is well suited for semiconductor, medical and optical applications.

#### **Typical Properties:**

To be used as a guide only, not as a specification. Different batches, conditions & applications yield differing results.

Cure condition: 150°C/1 Hour \* denotes test on lot acceptance basis Data below is not guaranteed.

### PHYSCIAL PROPERTIES:

\* Color (before cure): Part A: Clear/Colorless Part B: Amber

\* Consistency Pourable liquid \* Viscosity (23°C): @ 100 rpm 150 - 300 cPs Thixotropic Index: N/A

\* Glass Transition Temp: ≥ 95 °C (Dynamic Cure:20-200°C/ISO 25 Min; Ramp -10-200°C @ 20°C/Min)

Coefficient of Thermal Expansion (CTE):

Below Tg: 57 x 10<sup>-6</sup> in/in°C Above Tg: 210 x 10<sup>-6</sup> in/in°C

Shore D Hardness: 67 Lap Shear @ 23°C: 1,456

**Die Shear @ 23°C:** ≥ 10 **Kg** 3,400 **psi** 

 Degradation Temp:
 375 °C

 Weight Loss:
 @ 200°C
 0.06 %

 @ 250°C
 0.17 %

 @ 300°C
 0.50 %

@ 300°C 0.50 %
OperatingTemp: : Continuous: -55°C to 200°C

Intermittent: - 55°C to 300°C Storage Modulus: - 373,622 psi

Ion Content: CI: 26 ppm NA<sup>+</sup>: 15 ppm NH<sub>4</sub><sup>+</sup>: 22 ppm K<sup>+</sup>: 3 ppm

\* Particle Size: N/A

## **ELECTRICAL AND THERMAL PROPERTIES:**

Thermal Conductivity: N/A

Volume Resistivity @ 23°C:  $\geq 1 \times 10^{13}$  Ohm-cm

Dielectric Constant (1KHz): 3.36 Dissipation Factor (1KHz): 0.005

# **OPTICAL PROPERTIES @ 23°C:**

**Spectral Transmission:** ≥ 90% @ 600 - 1,000 nm

≥ 98% @ 1,000 - 6,800 **nm** 

**Refractive Index @ 23°C (uncured):** 1.5195 **@ 589 nm** 

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# EPO-TEK® 377 Advantages & Suggested Application Notes:

- Low viscosity epoxy with excellent handling characteristics. It can be used for encapsulating or potting. It may be applied by hand, pouring, spin coating, brushing, dipping, or automated dispensers.
- Certified for USP Class VI biocompatability and approved for ISO 10993.
- NASA approved, low outgassing epoxy <a href="http://outgassing.nasa.gov/">http://outgassing.nasa.gov/</a>
- Suggested Medical Applications / Scientific OEM:
- Opening Potting Pot
- ♦ Outstanding high temperature properties at 300°C and excellent solvent, chemical and moisture resistance, including autoclave, ETO, and gamma radiation.
- Suggested Semiconductor Grade epoxy:
- ♦ Spin coating at wafer level for MEMS fabrication of pressure sensors and accelerometers.
- ♦ Wafer-to-wafer bonding in CSP.
- ♦ Capillary underfill of flip chip packaged die.
- Suggested Optical grade epoxy, opto-electronic packaging:
- ♦ Transmission in NIR from 700 900 nm >95%.
- ♦ Glass seal, hermetic seal of glass plates in LCD fabrication.
- ♦ Hermetic seal of IR-filter window to aluminum cap of TO-Can in hybrid packaged IR sensors.
- Suggested Industrial: resist salt water, hydraulic fluids, motor oil, alcohol, 10% nitric acid, 10% sulfuric acid, 10% ammonia solution and most solvents.

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